IN THE UNITED STATES PATENT AND TRADEMARK OFFICE In re Application of: Yen-Ming Chen

Serial No.: 10/ 050,300

Group Art Unit: 2818

Examiner: Mai Huong C. Tran

Filed:

Jan. 15, 2002

In Response to Office Action

TECHTIGLOSY CENTER 2800

Dated: April 2, 2003

For:

Microelectronic Fabrication With Corrosion

Inhibited Bond Pad

Attorney Docket No.: 67,200-571

Certificate of Mailing

I hereby certify that this paper (along with any referred to as being attached or enclosed) is being deposited with the <u>United</u> States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to: Assistant Commissioner for Patents,

Washington, D.C. 20231,

Date: May 2, 2003

RESPONSE TO OFFICE ACTION

Assistant Commissioner for Patents Washington, D.C. 20231

Dear Sir:

In response to an Office Action mailed April 2, 2003 of a restriction requirement imposed by the Examiner, the Applicants hereby elect with traverse the prosecution of Group I, device claims, (claims 9-16).

Respectfully submitted,

Tung & Associates

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